

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Wen-Ching Chen : Group
Serial No: 10/662,432 : Art Unit #2878
Filed: 16 September 2003 : Examiner:
Title: FLIP CHIP PACKAGE STRUCTURE : K. Pyo
FOR AN IMAGE SENSOR AND AN
IMAGE SENSE MODULE WITH THE :
FLIP CHIP PACKAGE STRUCTURE

AMENDMENT

Mail Stop Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Responsive to the Office Action dated 24 May 2004, please amend the
above-referenced Patent Application as follows:

Amendments to the Claims are reflected in the Listing of Claims which
begins on page 2 of this paper.

Amendments to the Drawings begin on page 7 of this paper.

Amendments to the Specification begin on page 8 of this paper.

Remarks/Arguments begin on page 10 of this paper.

An Appendix which includes one replacement sheet is attached after page
13 of this paper.